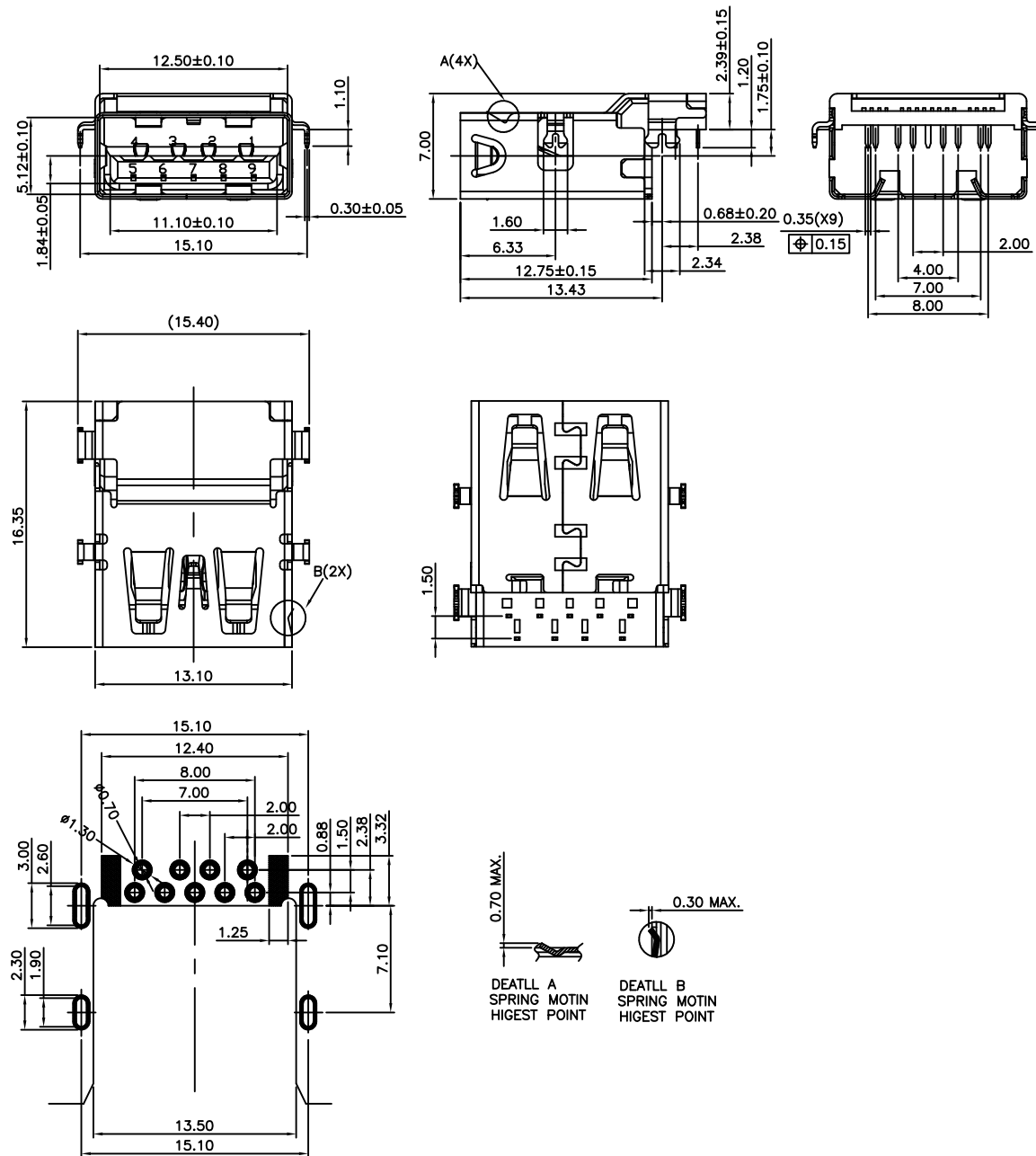




PIN NO.	1	2	3	4	
SIGNAL NAME	VBUS	D-	D+	PGND	
REMARK	USB 2.0 CONTACT PIN				
PIN NO.	5	6	7	8	9
SIGNAL NAME	SSRX-	SSRX+	GND	SSTX-	SSTX+
REMARK	USB 3.0 CONTACT PIN				

NOTE:

1. MATERIAL :

1.1 HOUSING: LCP +30%GF.

1.2 TERMINAL: C2680

1.3 SHELL:SUS

2. PLATING:

2.1 TERMINAL: NICKEL 30u" MIN UNDER PLATED OVERALL, GOLD PLATED ON THE CONTACT AREA.

50u" MATTE Tin ON THE SOLDERING AREA.

2.2 SHELL: NICKEL PLATING OVERALL

3. PART NO. DESCRIPTION:

HYC170-USBA09-175-XX

MATERIAL
4:LCP
9:PA9T

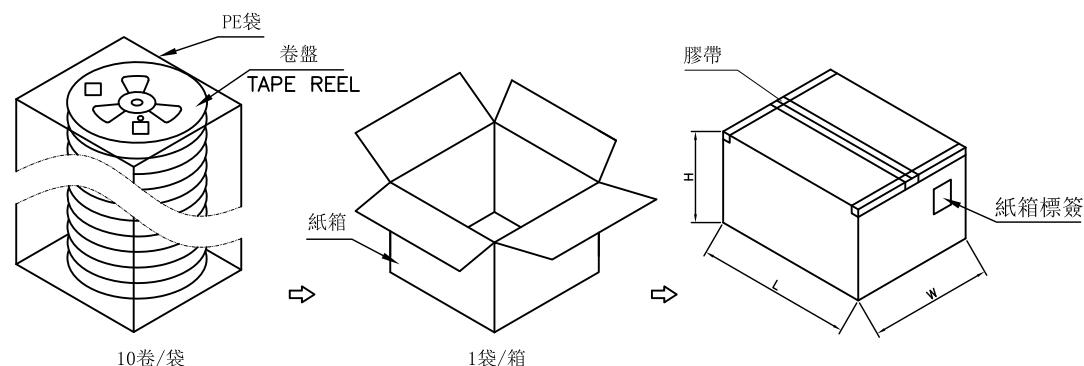
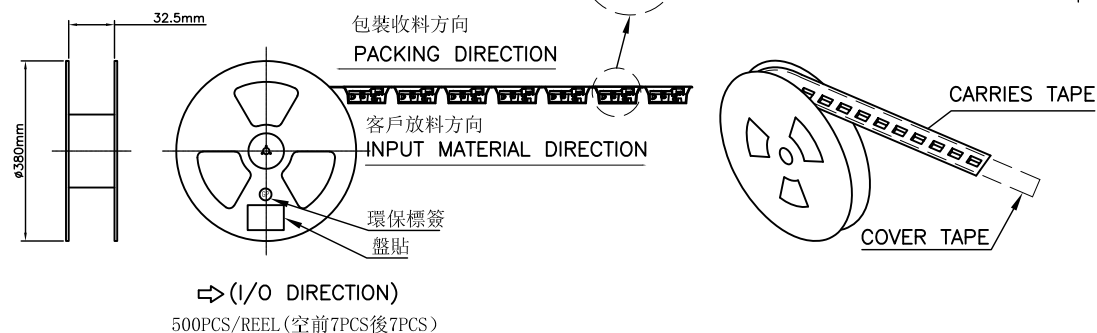
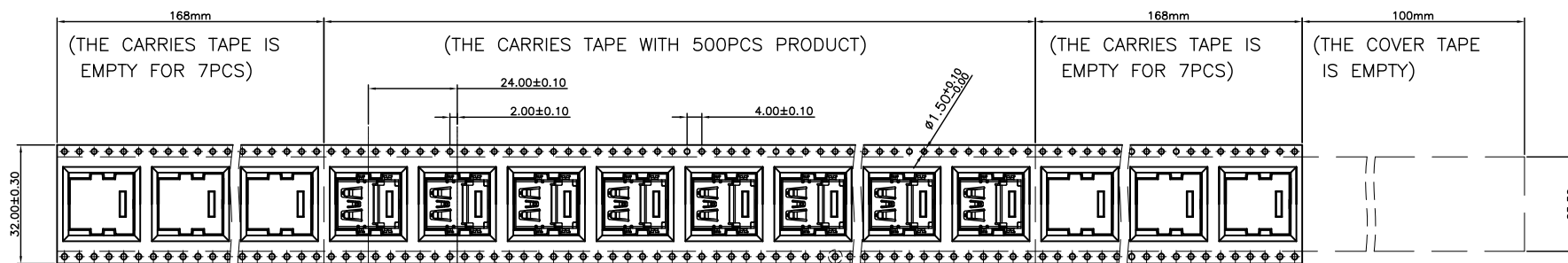
COLOR
1:BLACK
2:BLUE

TOLERANCE: ±0.05, THICKNESS: 1.2mm
RECOMMENDED PCB LAYOUT



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB 3.0 AF 沉板反向DIP CH-1.75	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC170-USBA09-175-XXB	MOLD NO.
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2511171512	SHEET NO. 1 OF 1



備注:

1. 防止漏裝，禁止碰歪產品錫腳。
2. 產品在CARRY TPAE中的方向須如圖所示。
3. COVER剝離力：0.1~0.7N.
4. 剝離角度為：165度~180度.
5. 剝離速度為：300mm/min.



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X" ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 包装图	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	
			SHEET NO.	1 OF 1